



Material Content Data Sheet



Sales Product Name		BTS282Z E3180A		Issued		19. July 2018		
MA#		MA000931510						
Package		PG-TO263-7-1		Weight*		1537.48 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	13.825	0.90	0.90	8992	8992
leadframe	non noble metal	iron	7439-89-6	0.810	0.05		527	
	inorganic material	phosphorus	7723-14-0	0.243	0.02		158	
	non noble metal	copper	7440-50-8	808.613	52.59	52.66	525933	526619
wire	non noble metal	aluminium	7429-90-5	4.597	0.30	0.30	2990	2990
encapsulation	organic material	carbon black	1333-86-4	8.723	0.57		5674	
	plastics	epoxy resin	-	95.954	6.24		62410	
	inorganic material	silicondioxide	60676-86-0	476.863	31.02	37.83	310159	378243
leadfinish	non noble metal	tin	7440-31-5	13.037	0.85	0.85	8479	8479
plating	non noble metal	nickel	7440-02-0	0.212	0.01		138	
	inorganic material	phosphorus	7723-14-0	0.001	0.00	0.01	1	138
glue	plastics	Polyimide	26023-21-2	0.157	0.01	0.01	102	102
solder	noble metal	silver	7440-22-4	0.202	0.01		132	
	non noble metal	tin	7440-31-5	0.162	0.01		105	
	non noble metal	lead	7439-92-1	7.732	0.50	0.52	5029	5266
heatspreader	non noble metal	iron	7439-89-6	0.106	0.01		69	
	inorganic material	phosphorus	7723-14-0	0.032	0.00		21	
	non noble metal	copper	7440-50-8	106.210	6.91	6.92	69081	69171
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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